

CMOS 4-Bit Magnitude Comparator

High Voltage Types (20-Volt Rating)

CD4585B is a 4-bit magnitude comparator designed for use in computer and logic applications that require the comparison of two 4-bit words. This logic circuit determines whether one 4-bit word (Binary or BCD) is "less than", "equal to", or "greater than" a second 4-bit word.

The CD4585B has eight comparing inputs (A3, B3, through A0, B0), three outputs (A <B,A = B,A > B) and three cascading inputs (A <B, A = B, A > B) that permit systems designers to expand the comparator function to 8, 12, 16......4N bits. When a single CD4585B is used, the cascading inputs are connected as follows: (A < B) = low, (A = B) = high, (A > B) = high.

Cascading these units for comparison of more than 4 bits is accomplished as shown in Fig. 13.

The CD4585B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (VDD)

POWER DISSIPATION PER PACKAGE (PD):

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

LEAD TEMPERATURE (DURING SOLDERING):

Features:

- Expansion to 8,12,16.....4N bits by cascading units
- Medium-speed operation:

compares two 4-bit words in 180 ns (typ.) at 10 V

- = 100% tested for guiescent current at 20 V
- Standardized symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 μA at 18 V over full package temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package temperature range) range) = 1 V at V_{DD} = 5 V

 Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

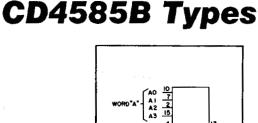
Voltages referenced to V_{SS} Terminal)-0.5V to +20V

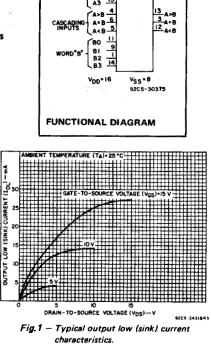
 FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)
 100mW

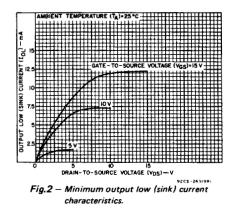
 OPERATING-TEMPERATURE RANGE (T_A)
 -55°C to +125°C

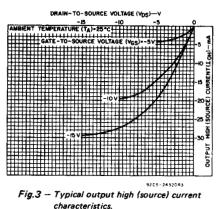
 STORAGE TEMPERATURE RANGE (T_{atg})
 -65°C to +150°C

Servo motor controls Process controllers





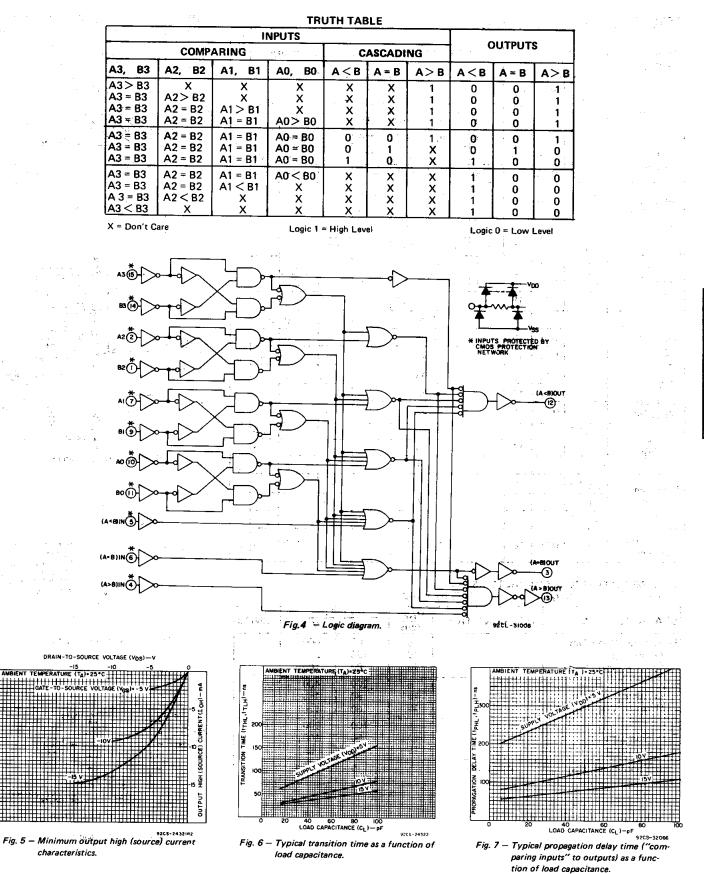




RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIN		
CHARACTERISTIC	Min.	Max.	UNITS
Supply-Voltage Range (For TA = Full Package-			
Temperature Range)	3	18	V

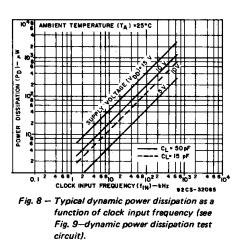


COMMERCIAL CMOS HIGH VOLTAGE ICS

3

STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC	c									C)	U N I T
	V _O (V)	VIN (V)	V _{DD} (V)	-55	-40	+85	+125	Min.	+25 Typ.	Max.	S
·	_	0,5	5	5		150	150	_	0.04	5	
Quiescent Device		0,10	10	10	10	300	300	_	0.04	10	
Current,	-	0,15	15	20	20	600	600	_	0.04	20	μA
IDD Max.	_	0,20	20	100	100	3000	3000	_	0.08	100	
	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	+	
Output Low (Sink) Current		0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source)	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mΑ
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage:	-	0,5	5		0	-	0	0.05			
Low-Level,	-	0,10	10		0	-	0	0.05			
VOL Max.	-	0,15	15		0	-	0	0.05	v		
Output	-	0,5	5		4	.95		4.95	5	-	
Voltage:	-	0,10	10		9	.95		9.95	10	-	
High-Level, V _{OH} Min.	-	0,15	15		14	.95		14.95	15	-	
Input Low	0.5,4.5	_	5			1.5		-	-	1.5	
Voltage	1,9	—	10			3		-		3	
V _{IL} Max.	1.5,13.5	_	15			4		-	-	4	l v
Input High	0.5,4.5	-	5		:	3.5		3.5	-	-	
Voltage,	1,9	-	10			7	-	-			
V _{IH} Min.	1.5,13.5	-	15			11		11	-	-	
Input Current I _{IN} Max.	_	0,18	18	±0.1	±0.1	±1	±1	-	±10 ^{—5}	±0.1	μΑ



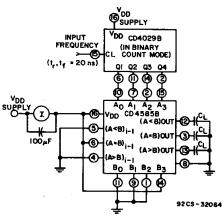


Fig. 9 - Dynamic power dissipation test circuit.

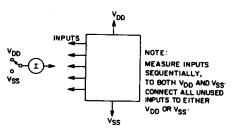




Fig. 10 - Input current test circuit.

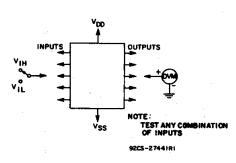


Fig. 11 - Input-voltage test circuit.

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^{\circ}C$; Input t_r , $t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}$, $R_L = 200 \text{ k}\Omega$

	T	Vnn	LIN	lits		
CHARACTERISTIC	TEST CONDITIONS	V _{DD} Volts	Тур.	Max.	UNITS	
Propagation Delay Time:		5	300	600		
Comparing Inputs to		10	125	250	1	
Outputs, tPHL, tPLH		15	80	160	ns	
		5	200	400	1	
Cascading Inputs to		10	80	160		
Outputs, tpHL, tpLH		15	60	120		
		5	100	200		
Transition Time,		10	50	100	ns	
^t THL ^{, t} TLH		15	40	80		
Input Capacitance, CIN	Any Input	* ¹ :	- 5	7.5	ρF	
· · · · · · · · · · · · · · · · · · ·	··· • ································			I		

CD4585B Types

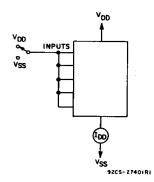


Fig. 12 - Quiescent-device-current test circuit.

TERMINAL ASSIGNMENT

16 V_{DD}

14 - 83

13

12

11 ---- 80

10 --- AO

9 ---- 81

9205-31006

-(A>B)OUT

- (A<8)OUT

82

A2 - 2

3

4

5

6

8

TOP VIEW

(A=B)OUT-

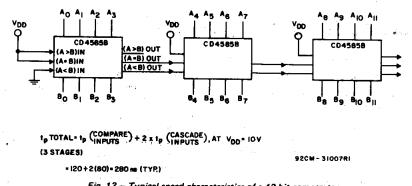
(A>B) IN-

(A<8)IN -

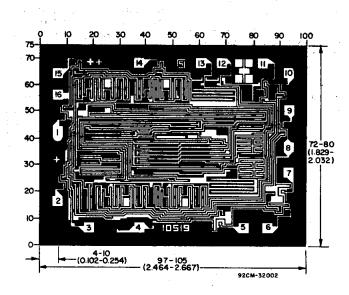
(A-B)IN-

AI --- 7

vss







Dimensions and Pad Layout for CD4585BH

2-

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
7703702EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Non-Green	SNPB	N / A for Pkg Type	-55 to 125	7703702EA CD4585BF3A	Samples
CD4585BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4585BE	Samples
CD4585BEE4	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4585BE	Samples
CD4585BF3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Non-Green	SNPB	N / A for Pkg Type	-55 to 125	7703702EA CD4585BF3A	Samples
CD4585BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4585B	Samples
CD4585BPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM585B	Samples
CD4585BPWE4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM585B	Samples
CD4585BPWG4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM585B	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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10-Dec-2020

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4585B, CD4585B-MIL :

- Catalog: CD4585B
- Military: CD4585B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

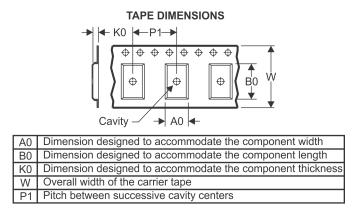
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4585BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

3-Dec-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4585BNSR	SO	NS	16	2000	367.0	367.0	38.0

PW0016A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



PW0016A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0016A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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